Product Specification

QDD-QDD-C to QDD-QDD-C Passive Direct Attach Copper Twinax Cable

PN: QDD-QDD-C

Features

- Hot Pluggable QSFP-DD form factor
- Wire AWG:30AWG,28AWG
- Available length range 1m~3m
- Operating data rate 425Gbps
- Power supply：+3.3V
- Max power dissipation <0.1W
- 8-Channel Full-Duplex Passive Copper Cable
- Commercial temperature range 0°C to 70°C

Compliance

- Compliant with QSFP-DD MSA
- Compliant with Electrical Interface SFF-8679
- IEEE802.3bj,IEEE802.3cd
- RoHS

Applications

- High Performance Computing (HPC)
- Data Center & Networking Equipment
- Servers/Storage Devices
- Switches with QSFP-DD ports

Description

The QDD-QDD-C Direct Attach Cable (DAC) is a high-performance, cost-effective solution designed to meet the demands of next-generation data centers and HPC environments. Supporting data rates of up to 400Gbps, this cable ensures ultra-fast data transfer with minimal latency, making it ideal for bandwidth-intensive applications. Its plug-and-play design simplifies deployment, while its low power consumption and robust construction make it an energy-efficient and durable choice for modern infrastructure.

This cable is perfect for interconnecting switches, routers, and servers within high-density data centers, as well as supporting HPC clusters and cloud computing environments. Available in various lengths, the QSFP-DD 400G DAC provides flexibility for different deployment scenarios, ensuring seamless connectivity across racks and systems. Its compliance with IEEE 802.3bs and QSFP-DD MSA standards guarantees interoperability with a wide range of networking equipment, offering a reliable and future-proof solution.

By delivering high-speed, low-latency connectivity, the QSFP-DD 400G DAC enhances network performance and scalability while reducing capital and operational expenses. Its cost-effective design eliminates the need for additional transceivers and fiber optics, making it an economical choice for organizations seeking to optimize their infrastructure. Whether for data centers, HPC, or enterprise networks, this cable ensures efficient data exchange and supports the growing demands of modern digital ecosystems.

Product performance Specifications

1、Basic Product Characteristics

Parameter	Symbol	Min	Typ.	Max	Unit
Storage Temperature	T_S	-40		85	°C
Operating Case Temperature	T_C	0		70	°C
Relative Humidity	RH	5		85	%
Supply Voltage	V_{CC}	-0.3	3.3	3.6	V
Data Rate	DR		425		Gbp/s
Power Consumption	P			0.1	W

2、Product Optical and Electrical Characteristics

Test Type	Test Item	24AWG	26AWG	28AWG	30AWG
Electrical Characteristics	Differential impedance	100±5Ω at TDR	100±5Ω	100±5Ω	100±5Ω at TDR
	Mutual capacitance	14pF/ft nominal	14pF/ft nominal	14pF/ft nominal	14pF/ft nominal
	Time delay	1.31ns/ft nominal, (4.3ns/m) nominal	1.35ns/ft nominal	1.35ns/ft nominal	1.35ns/ft nominal, (4.3ns/m) nominal
	Time delay skew (within pairs)	80ps/10m maximum	120ps/8.5m maximum	120ps/7m maximum	50ps/5.5m maximum
	Time delay skew (between pairs)	350ps/10m maximum	500ps/8.5m maximum	500ps/7m maximum	350ps/5.5m maximum
	Attenuation	10dB/10m maximum at 1.25Ghz	10dB/8.5m maximum at 1.25Ghz	10dB/7m maximum at 1.25Ghz	8.4dB/5.5m maximum at 1.25Ghz
	Conductor DC Resistance	0.026Ω /ft maximum at 20°C	0.04Ω /ft maximum at 20°C	0.06Ω/ft maximum at 20°C	0.01Ω/ft maximum at 20°C
Physical Characteristics	Conductors (two pair)	24AWG Solid, Silver plated copper	26AWG Solid, Silver plated copper	28AWG Solid, Silver plated copper	30AWG Solid, Silver plated copper
	Insulation	Foam polyolefin	Foam polyolefin	Foam polyolefin	Foam polyolefin
	Pair drain wire	26AWG Solid, Silver plated copper	28AWG Solid, Silver plated copper	30AWG Solid, Silver plated copper	30AWG Solid, Silver plated copper
	Overall cable shield	Aluminum/polyester tape, 125% coverage, Tin plated copper braid, 38AWG, 85% coverage	Aluminum/polyester tape, 125% coverage, Tin plated copper braid, 38AWG, 85% coverage	Aluminum/polyest er tape, 125% coverage,Tin plated copper braid, 38AWG, 85% coverage	Aluminum/polyester tape, 125% coverage,Tin plated copper braid, 38AWG, 85% coverage
	Outer diameter	6.0mm	5.2mm	4.7mm	4.2mm

Recommended Host Board Power Supply Circuit

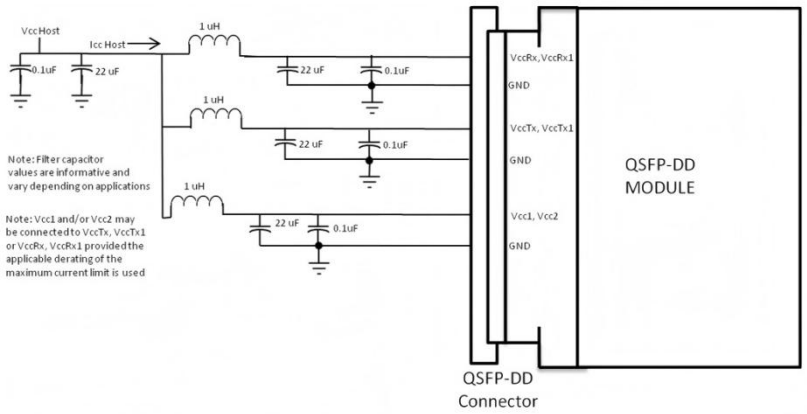


Figure 1: Recommended Host Board Power Supply Circuit

Recommended Interface Circuit

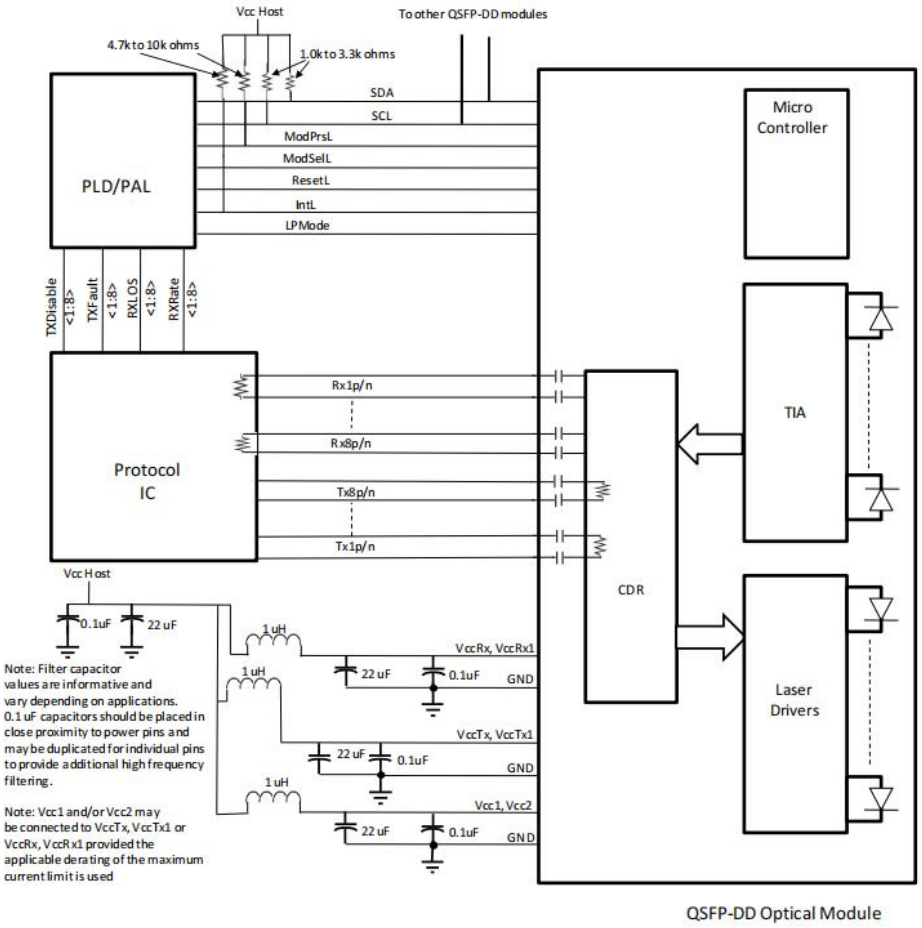


Figure2: Recommended Interface Circuit

Pin-out Definition

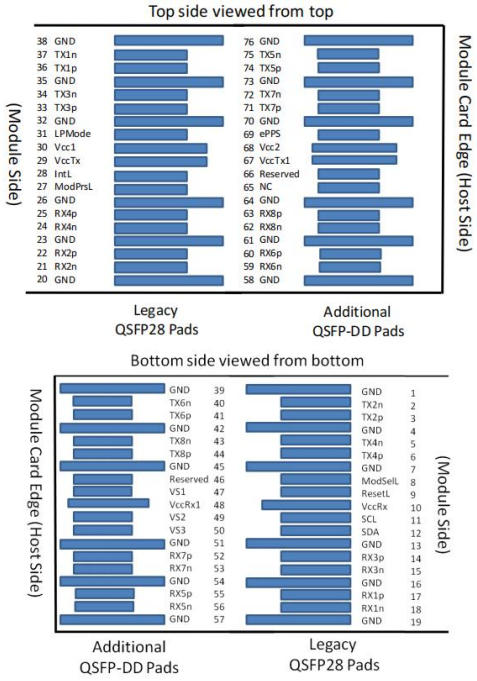


Figure3:Pin view

Pin Function Definitions

Pin	Logic	Symbol	Description	Note
1		GND	Ground	1
2	CML-I	Tx2n	Transmitter Inverted Data Input	
3	CML-I	Tx2p	Transmitter Non-Inverted Data Input	
4		GND	Ground	1
5	CML-I	Tx4n	Transmitter Inverted Data Input	
6	CML-I	Tx4p	Transmitter Non-Inverted Data Input	
7		GND	Ground	1
8	LVTTL-I	ModSelL	Module Select	
9	LVTTL-I	ResetL	Module Reset	
10		Vcc Rx	+3.3V Power Supply Receiver	2
11	LVCMOS-I/O	SCL	2-wire serial interface clock	
12	LVCMOS-I/O	SDA	2-wire serial interface data	
13		GND	Ground	1
14	CML-O	Rx3p	Receiver Non-Inverted Data Output	
15	CML-O	Rx3n	Receiver Inverted Data Output	
16		GND	Ground	1
17	CML-O	Rx1p	Receiver Non-Inverted Data Output	

18	CML-O	Rx1n	Receiver Inverted Data Output	
19		GND	Ground	1
20		GND	Ground	1
21	CML-O	Rx2n	Receiver Inverted Data Output	
22	CML-O	Rx2p	Receiver Non-Inverted Data Output	
23		GND	Ground	1
24	CML-O	Rx4n	Receiver Inverted Data Output	
25	CML-O	Rx4p	Receiver Non-Inverted Data Output	
26		GND	Ground	1
27	LVTTL-O	ModPrsL	Module Present	
28	LVTTL-O	IntL/RxLOSL	Interrupt. Optionally configurable as RxLOSL via the management interface (SFF-8636)	
29		VccTx	+3.3V Power supply transmitter	2
30		Vcc1	+3.3V Power supply	2
31	LVTTL-I	InitMode	Initialization mode; In legacy QSFP applications, the InitMode pad is called LPMODE	
32		GND	Ground	1
33	CML-I	Tx3p	Transmitter Non-Inverted Data Input	
34	CML-I	Tx3n	Transmitter Inverted Data Input	
35		GND	Ground	1
36	CML-I	Tx1p	Transmitter Non-Inverted Data Input	
37	CML-I	Tx1n	Transmitter Inverted Data Input	
38		GND	Ground	1
39		GND	Ground	1
40	CML-I	Tx6n	Transmitter Inverted Data Input	
41	CML-I	Tx6p	Transmitter Non-Inverted Data Input	
42		GND	Ground	1
43	CML-I	Tx8n	Transmitter Inverted Data Input	
44	CML-I	Tx8p	Transmitter Non-Inverted Data Input	
45		GND	Ground	1
46		Reserved	For future use	3
47		VS1	Module Vendor Specific 1	3
48		VccRx1	3.3V Power Supply	2
49		VS2	Module Vendor Specific 2	3
50		VS3	Module Vendor Specific 3	3
51		GND	Ground	1
52	CML-O	Rx7p	Receiver Non-Inverted Data Output	
53	CML-O	Rx7n	Receiver Inverted Data Output	
54		GND	Ground	1
55	CML-O	Rx5p	Receiver Non-Inverted Data Output	
56	CML-O	Rx5n	Receiver Inverted Data Output	
57		GND	Ground	1

58		GND	Ground	1
59	CML-O	Rx6n	Receiver Inverted Data Output	
60	CML-O	Rx6p	Receiver Non-Inverted Data Output	
61		GND	Ground	1
62	CML-O	Rx8n	Receiver Inverted Data Output	
63	CML-O	Rx8p	Receiver Non-Inverted Data Output	
64		GND	Ground	1
65		NC	No Connect	3
66		Reserved	For future Use	3
67		VccTx1	3.3V Power Supply	2
68		Vcc2	3.3V Power Supply	2
69		Reserved	For future Use	3
70		GND	Ground	1
71	CML-I	Tx7p	Transmitter Non-Inverted Data Input	
72	CML-I	Tx7n	Transmitter Inverted Data Input	
73		GND	Ground	1
74	CML-I	Tx5p	Transmitter Non-Inverted Data Input	
75	CML-I	Tx5n	Transmitter Inverted Data Input	
76		GND	Ground	1

Note1:QSFP-DD uses common ground (GND)for all signals and supply (power). All are common within the QSFP-DD module and all module voltages are referenced to this potential unless otherwise noted. Connect these directly to the host board signal common ground plane.

Note2: VccRx, VccRx1, Vcc1, Vcc2, VccTx and VccTx1 shall be applied concurrently. Requirements defined for the host side of the Host Card Edge Connector are listed in Table 6. VccRx, VccRx1, Vcc1, Vcc2, VccTx and VccTx1 may be internally connected within the module in any combination. The connector Vcc pins are each rated for a maximum current of 1000 mA.

Note3: All Vendor Specific, Reserved and No Connect pins may be terminated with 50 ohms to ground on the host. Pad 65 (No Connect) shall be left unconnected within the module. Vendor specific and Reserved pads shall have an impedance to GND that is greater than 10 Kohms and less than 100 pF.

Monitoring Specification

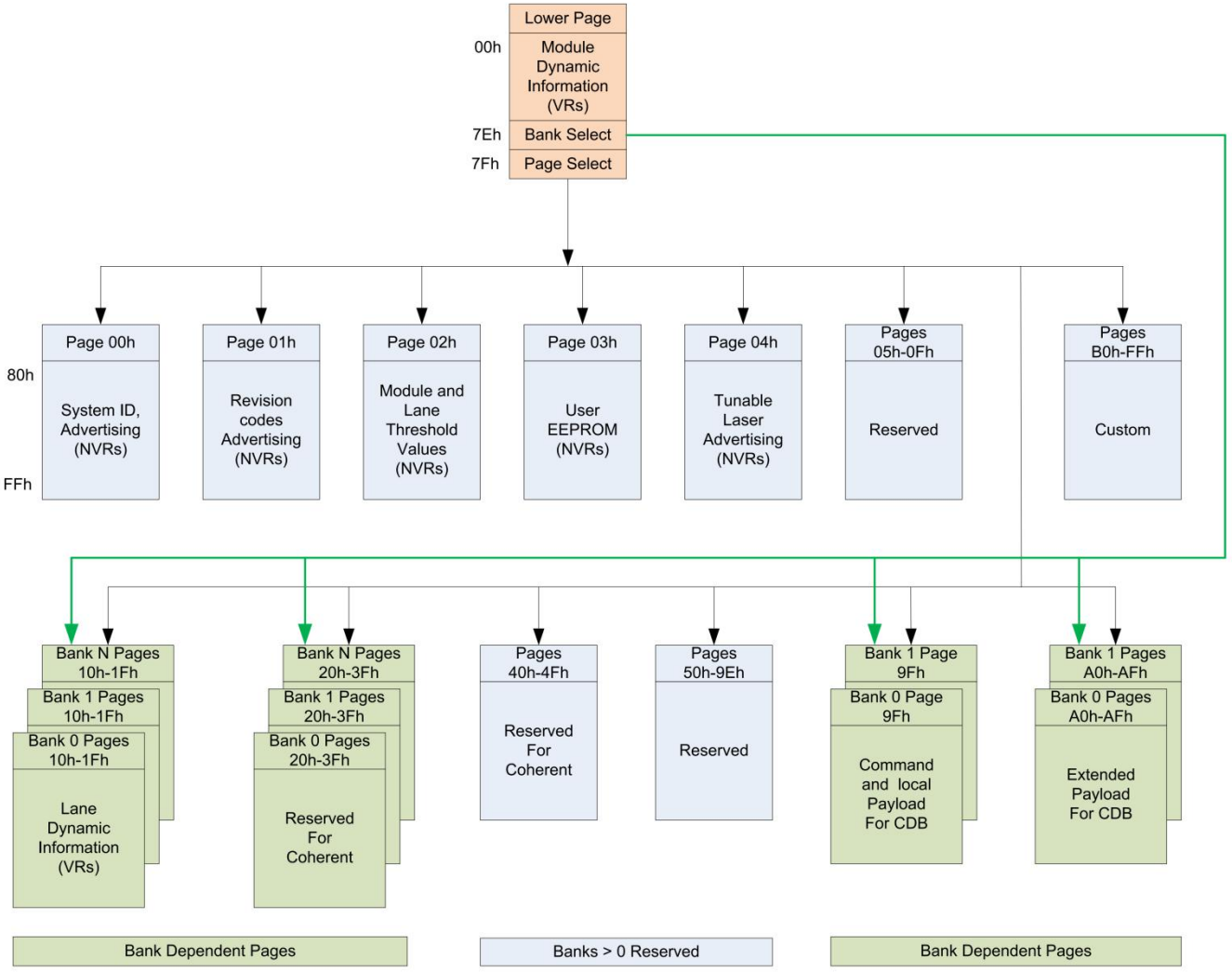


Figure4: Memory map

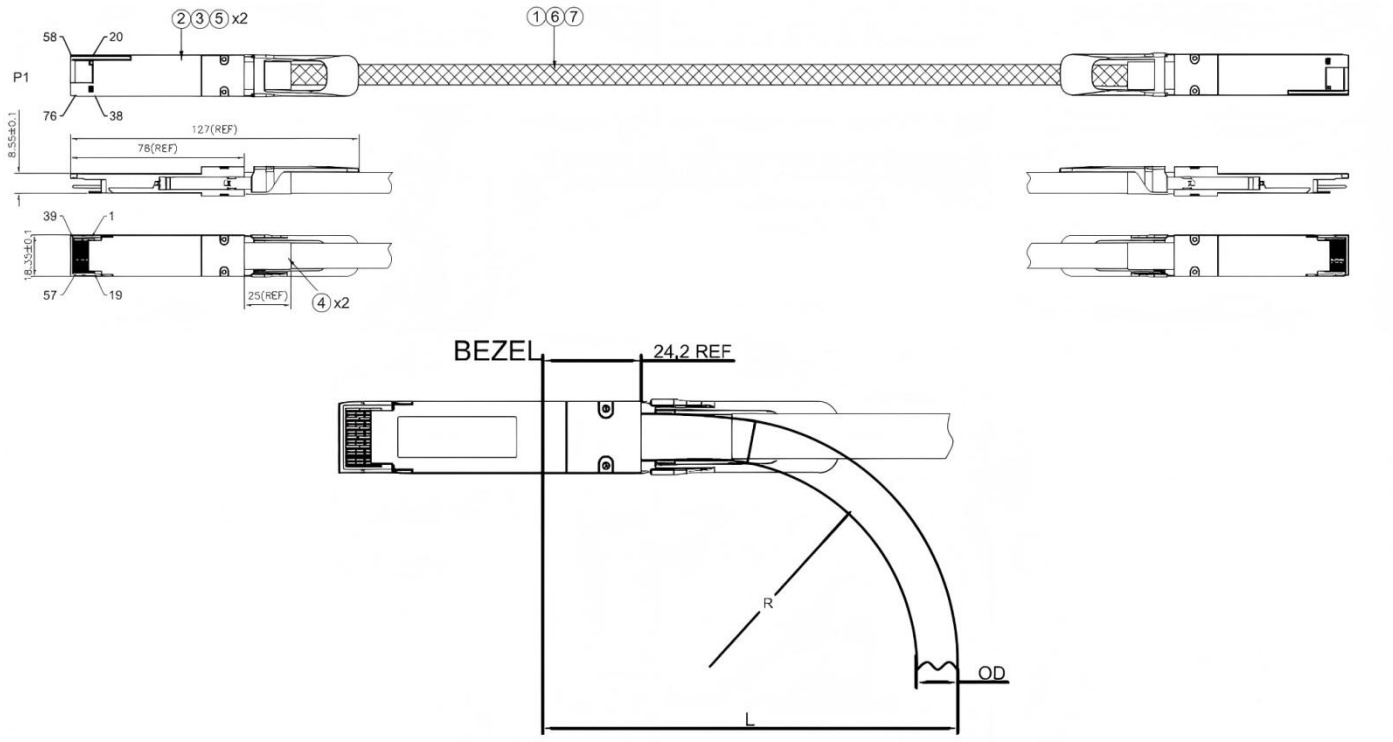
Memory map Table

Byte	Unit	Name	Description
Lower Page 00h			
0	1	Identifier	Identifier - Type of Serial Module - See SFF-8024.
1	1	Revision Compliance	Identifier – CMIS revision; the upper nibble is the whole number part and the lower nibble is the decimal part. Example: 01h indicates version 0.1, 21h indicates version 2.1.
2-3	2	ID and Status Area	Flat mem indication, CLEI present indicator, Maximum TWI speed, Current state of Module, Current state of the Interrupt signal.

4-7	4	Lane Flag Summary	Flag summary of all lane flags on pages 10h-1Fh.
8-13	6	Module-Level Flags	All flags that are not lane or data path specific.
14-25	12	Module-Level Monitors	Monitors that are not lane or data path specific.
26-30	5	Module Global Controls	Controls applicable to the module as a whole
31-36	6	Module-Level Flag Masks	Masking bits for the Module-Level flags
37-38	2	CDB Status Area	Status of most recent CDB command
39-40	2	Module Firmware Version	Module Firmware Version.
41-63	23	Reserved Area	Reserved for future standardization
64-82	19	Custom Area	Vendor or module type specific use
83-84	2	Inactive Firmware Version	Version Number of Inactive Firmware. Values of 00h indicates module supports only a single image.
85-117	33	Application Advertising	Combinations of host and media interfaces that are supported by module data path(s)
118-125	8	Password Entry and Change	Password Entry and Change
126	1	Bank Select Byte	Bank address of currently visible Page
127	1	Page Select Byte	Page address of currently visible Page
Upper Page 00h			
128	1	Identifier	Identifier - Type of Serial Module - See SFF-8024.
129-144	16	Vendor name	Vendor name (ASCII)
145-147	2	Vendor OUI	Vendor IEEE company ID
148-163	16	Vendor PN	Part number provided by vendor (ASCII)
164-165	8	Vendor rev	Revision level for part number provided by vendor (ASCII)
166-181	10	Vendor SN	Vendor Serial Number (ASCII)
182-183	2	Date code year	ASCII code, two low order digits of year (00=2000)
184-185	2	Date code month	ASCII code digits of month (01=Jan through 12=Dec)
186-187	2	Date code day of month	ASCII code day of month (01-31)
188-189	2	Lot code	ASCII code, custom lot code, may be blank
190-199	10	CLEI code	Common Language Equipment Identification code
200-201	2	Module power characteristics	Module power characteristics
202	1	Cable assembly length	Cable assembly length
203	1	Media Connector Type	Media Connector Type
204	1	5 GHz attenuation	Passive copper cable attenuation at 5 GHz in 1 dB increments
205	1	7 GHz attenuation	Passive copper cable attenuation at 7 GHz in 1 dB increments
206	1	12.9 GHz attenuation	Passive copper cable attenuation at 12.9 GHz in 1 dB increments
207	1	25.8 GHz attenuation	Passive copper cable attenuation at 25.8 GHz in 1 dB increments
208-209	2	Reserved	Reserved
210-211	2	Cable Assembly Lane Information	Cable Assembly Lane Information

212	1	Media Interface Technology	Media Interface Technology
213-220	8	Reserved	Reserved
221	1	Custom	Custom
222	1	Checksum	Includes bytes 128-221
223-255	33	Custom Info NV	Custom Info NV

Mechanical Dimension



Note:

- Unit: mm
- Tolerance: φ0.1mm if not shown
- Latch color: black
- When L≤2m, the tolerance is ±25mm, when L>2m, the tolerance is ±50mm

Waring:

- The transceiver optics is supplied with a dust cover. This plug protects the transceiver optics during standard manufacturing processes by preventing contamination from air borne particles.It is recommended that the dust cover remain in the transceiver whenever an optical fiber connector is not inserted.
- Handling Precautions: This device is susceptible to damage as a result of electrostatic discharge (ESD). A static free environment is highly recommended. Follow guidelines according to proper ESD procedures.
- Laser Safety: Radiation emitted by laser devices can be dangerous to human eyes. Avoid eye exposure to direct or indirect radiation.